

EddyCus[®] TF map 2530MT – Metal Thickness Imaging Device

P_T_2530MT_21



Highlights

- ▶ High resolution (5 – 1,000,000 points)
- ▶ Contact-free (4PP replacement)
- ▶ Accurate with nanometer resolution
- ▶ High speed (0.5 to 30 minutes)
- ▶ Enables process wafer measurement
- ▶ Mapping of encapsulated layers
- ▶ Integrity and defect imaging

Processes

- ▶ Deposition (PVD, evaporation, plating, CVD, ALD etc.)
- ▶ Layer and material modification (implantation, doping, annealing)
- ▶ Layer removal (CMP, etching, scribing etc.)

Applications

- ▶ Semiconductor industry
- ▶ Electronic industry
- ▶ Metallization in photovoltaics
- ▶ Batteries, fuel cells, capacitors
- ▶ Boards and panels (PCB, WLP, PLP)
- ▶ Mirrors and lenses
- ▶ Barrier films
- ▶ EMC/EMI Shielding
- ▶ Heating and de-icing films
- ▶ Medical applications

Materials

- ▶ Metal films
- ▶ Metal meshes
- ▶ Metal substrates
- ▶ Alloy films
- ▶ Alloy substrates

SURAGUS GmbH
Maria-Reiche-Strasse 1
01109 Dresden
Germany

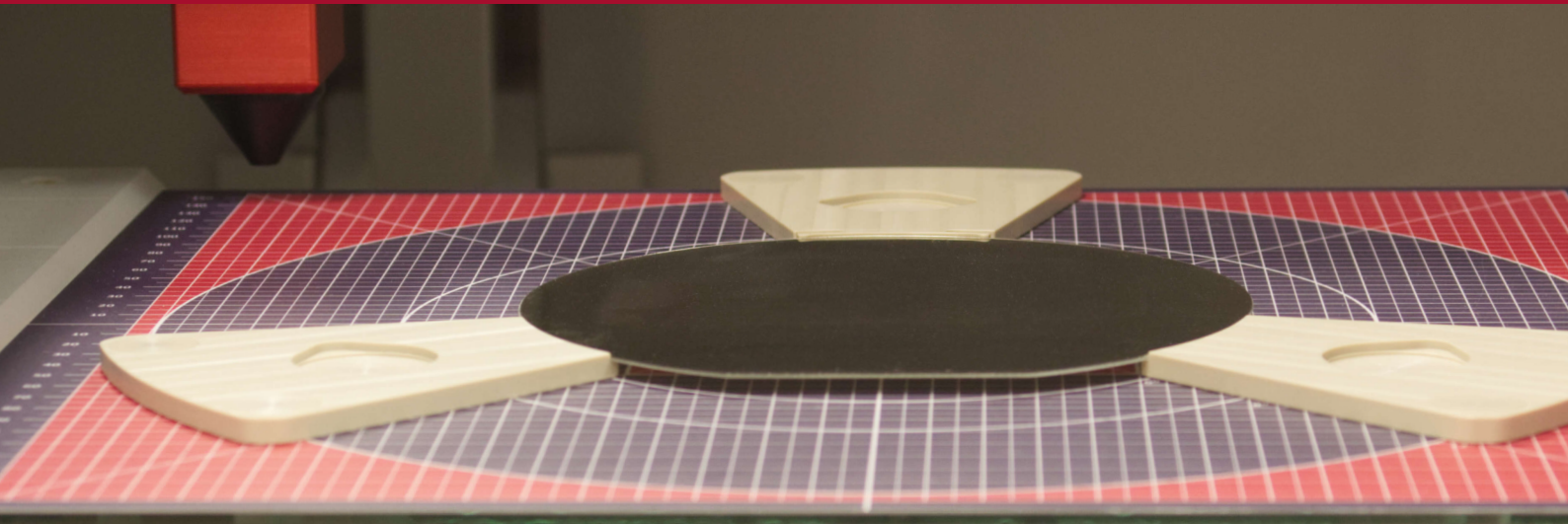
上海昊量光电设备有限公司

中国区代理

官网: www.auniontech.com 电话: 021-34241961
邮箱: info@auniontech.com
地址: 上海市徐汇区虹梅路2007号远中产业园三期6号楼3楼

Engineered and Made in Germany 





Measurement technology	Non-contact eddy current sensor
Substrates	Wafer, glass, foil, etc.
Max. scanning area	12 inch / 300 mm x 300 mm (larger upon request)
Edge effect correction / exclusion	2 – 10 mm (depending on size, range, setup and requirements)
Max. sample thickness / sensor gap	3 / 5 / 10 / 25 mm (defined by the thickest sample)
Metal thickness range	Low 1 – 10 nm; 2 – 5 % accuracy
Accuracies depend on the selected setup and the type / conductivity of the metal (e.g. copper, aluminum, silver)	Standard 10 – 1,000 nm; 1 – 3 % accuracy High 1 – 100 μm; 0.5 – 3 % accuracy
Metal thickness calibration	Direct thickness calibration / sheet resistance conversion
Sheet resistance range (optional)	0.1 mOhm/sq – 100,000 Ohm/sq (in 5 ranges)
Scanning pitch (X and Y)	1 / 2.5 / 5 / 10 / 25 mm
Scanning time	8 inch / 200 mm x 200 mm in 1.5 to 15 minutes (1 – 10 mm pitch) 12 inch / 300 mm x 300 mm in 2 to 15 minutes (2.5 – 25 mm pitch)
Device dimensions (w/h/d) / weight	31.5" x 19.1" x 33.5" / 799 mm x 486 mm x 850 mm / 90 kg
Further available features / other tool configurations	Sheet resistance measurement / conductivity / resistivity / anisotropy / permeability (<i>beta</i>)

Device Control and Software

- ▶ Pre-defined measurement and product recipes (sizes, pitches, thresholds)
- ▶ Line scan, histogram and area analysis
- ▶ Black and colored image coding
- ▶ Csv & pdf export
- ▶ SPC summary and export
- ▶ 3 user levels
- ▶ Material database for parameter conversion
- ▶ Edge effect compensation
- ▶ Storage and import of data
- ▶ Export of data sets (e.g. to EddyEva, MS Excel, Origin)

